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# 1.2W AUDIO POWER AMPLIFIER WITH ACTIVE-LOW SHUTDOWN MODE

June 2014

#### **DESCRIPTION**

The IS31AP4990D has been designed for demanding audio applications such as mobile phones and permits the reduction of the number of external components.

It is capable of delivering 1.2W of continuous RMS output power into an  $8\Omega$  load @ 5V.

An externally-controlled shutdown mode reduces the supply current to less than  $1\mu A$ . It also includes internal thermal shutdown protection.

The unity-gain stable amplifier can be configured by external gain setting resistors.

#### **FEATURES**

- Operating from V<sub>CC</sub> = 2.7V ~ 5.5V
- 1.2W output power @ V<sub>CC</sub> = 5V, THD+N= 1%,
- f = 1kHz, with  $8\Omega$  load
- Ultra-low consumption in shutdown mode (1µA)
- Near-zero pop & click
- Ultra-low distortion
- Unity gain stable
- UTQFN-9L (1.5mm × 1.5mm) package

### **APPLICATIONS**

- Mobile phones
- PDAs
- Portable electronic devices
- Notebook computer

### **TYPICAL APPLICATION CIRCUIT**

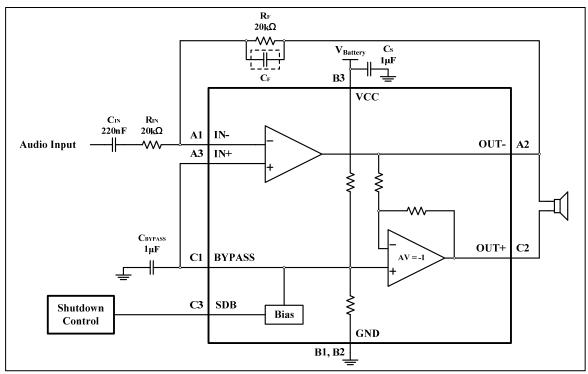


Figure 1 Typical Application Circuit (Single-ended Input)



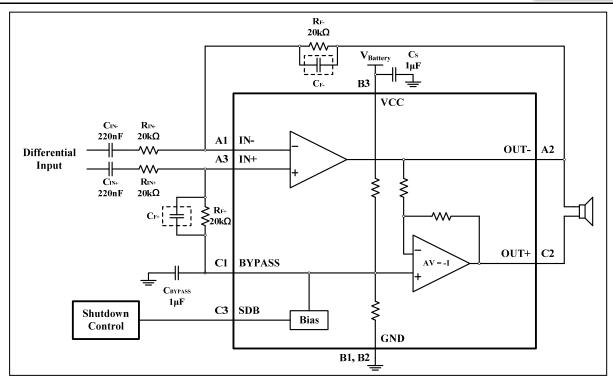


Figure 2 Typical Application Circuit (Differential Input)

# IS31AP4990D



# **PIN CONFIGURATION**

Package	Pin Configuration (Top View)		
UTQFN-9L	• IN- OUT- IN+ (A1) (A2) (A3) GND GND VCC (B1) (B2) (B3) BYPASS OUT+ SDB (C1) (C2) (C3)		

# **PIN DESCRIPTION**

No.	Pin	Function Description		
A1	IN-	Negative input of the first amplifier. Connected to the feedback resistor $R_{\text{F-}}$ and to the input resistor $R_{\text{IN-}}$ .		
A2	OUT-	Negative output. Connected to the load and to the feedback resistor $\ensuremath{R}_{\ensuremath{F}\ensuremath{-}}.$		
А3	IN+	Positive input of the first amplifier.		
B1,B2	GND	Ground.		
B3	VCC	Supply voltage.		
C1	BYPASS	Bypass capacitor pin which provides the common mode voltage $(V_{\text{CC}}/2)$ .		
C2	OUT+	Positive output. Connected to the load.		
C3	SDB	The device enters in shutdown mode when a low level is applied on this pin.		





ORDERING INFORMATION Industrial Range: -40°C to +85°C

Order Part No.	Package	QTY/Reel	
IS31AP4990D-UTLS2-TR	UTQFN-9, Lead-free	3000	

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a.) the risk of injury or damage has been minimized;

b.) the user assume all such risks; and

c.) potential liability of Integrated Silicon Solution, Inc is adequately protected under the circumstances

# IS31AP4990D



### **ABSOLUTE MAXIMUM RATINGS**

Supply voltage, V <sub>CC</sub>	−0.3V ~ +6.0V
Voltage at any input pin	-0.3V ~ V <sub>CC</sub> +0.3V
Maximum junction temperature, T <sub>JMAX</sub>	150°C
Storage temperature range, T <sub>STG</sub>	−65°C ~ +150°C
Operating temperature range, T <sub>A</sub>	-40°C ~ +85°C
ESD (HBM)	7kV
ESD (CDM)	500V

### Note:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other condition beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# **ELECTRICAL CHARACTERISTICS**

 $T_A$  = -40°C ~ +85°C,  $V_{CC}$  = 2.7V ~ 5.5V, unless otherwise noted. Typical value are  $T_A$  = +25°C.

Symbol	Parameter	Condition		Min.	Тур.	Max.	Unit	
V <sub>CC</sub>	Power supply				2.7		5.5	V
I <sub>CC</sub>	Quiceant aurrent	$V_{CC}$ = 5V, $V_{IN}$ = 0V, $I_{O}$ = 0A, no load			3.8	6.4	mA	
	Quiescent current	$V_{CC}$ = 3V, $V_{IN}$ = 0V, $I_{O}$ = 0A, no load				2.8		5.1
I <sub>SD</sub>	Shutdown current	V <sub>SDB</sub> = GNI	D, no load				1	μΑ
V <sub>IH</sub>	Shutdown voltage input high			1.4			V	
V <sub>IL</sub>	Shutdown voltage input low					0.4	V	
V <sub>OS</sub>	Output offset voltage						25	mV
	Output power (8Ω)	V <sub>CC</sub> = 5V	THD+N =	1%, f = 1kHz		1.20		W
Ро			THD+N =	: 10%, f = 1kHz		1.50		
		V <sub>CC</sub> = 3V	THD+N =	: 1%, f = 1kHz		0.418		
			THD+N =	10%, f = 1kHz		0.525		
4	Malas and Paras (Nata 4)	$V_{CC} = 5V$ , $C_{BYPASS} = 1\mu F$			115		ms	
$t_{WU}$	Wake-up time (Note 1)	V <sub>CC</sub> = 3V, C <sub>BYPASS</sub> = 1μF			102			
TUD.N	Total harmonic distortion +	$V_{CC}$ = 5V, $P_O$ = 0.5Wrms, $f$ = 1kHz			0.23		%	
THD+N	noise (Note 1)	$V_{CC}$ = 3V, Po = 0.3Wrms, f = 1kHz			0.15			
	Power supply rejection ratio (Note 1)	$V_{CC} = 5V$ $V_{Ripple p-p} = 200 \text{mV}$ Input grounded $f = 217 \text{Hz}$ $f = 1 \text{kHz}$			61			
DODD				f = 1kHz		65		dB
PSRR		$V_{CC} = 3.6V, 4.2V$ $V_{Ripple p-p} = 200 \text{mV}$		f = 217Hz		62		
				f = 1kHz		66		

Note 1: Guaranteed by design.



### TYPICAL PERFORMANCE CHARACTERISTIC

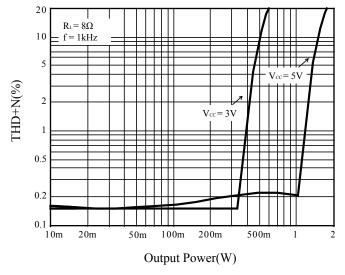


Figure 3 THD+N vs. Output Power

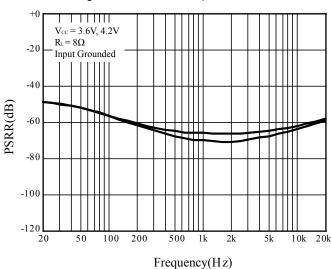


Figure 5 PSRR vs. Frequency

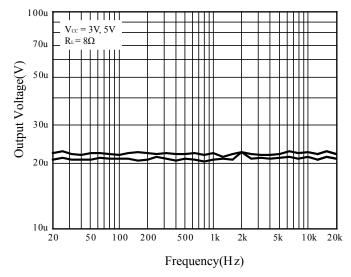


Figure 7 Noise Floor

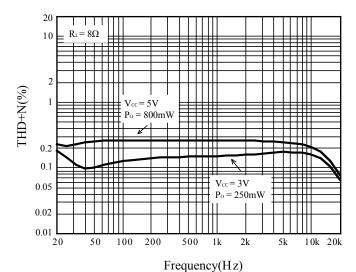


Figure 4 THD+N vs. Frequency

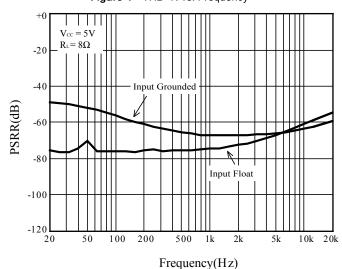


Figure 6 PSRR vs. Frequency

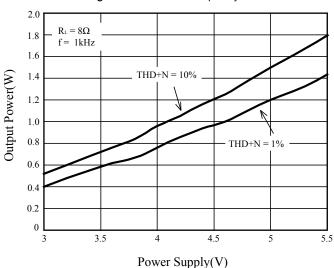


Figure 8 Output Power vs. Power Supply

# IS31AP4990D



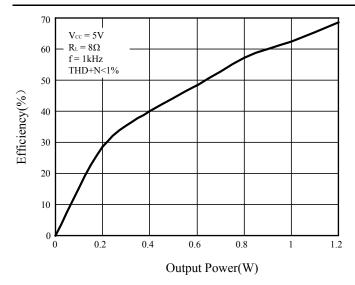


Figure 9 Efficiency vs. Output Power

# ISSI

### **APPLICATION INFORMATION**

### **BTL CONFIGURATION PRINCIPLE**

The IS31AP4990D is a monolithic power amplifier with a BTL output type. BTL (bridge tied load) means that each end of the load is connected to two single-ended output amplifiers. Thus, we have:

Single-ended output 
$$1 = V_{OUT+} = V_{OUT}(V)$$

Single ended output 
$$2 = V_{OUT} - = -V_{OUT}(V)$$

and 
$$V_{OUT+}$$
 -  $V_{OUT-}$  =  $2V_{OUT}$  (V)

The output power is:

$$P_{OUT} = \frac{(2V_{OUT_{RMS}})^2}{R_L}$$

For the same power supply voltage, the output power in BTL configuration is four times higher than the output power in single ended configuration.

### **GAIN IN A TYPICAL APPLICATION SCHEMATIC**

The typical application schematic is shown in Figure 1 on page 1.

In the flat region (no  $C_{\text{IN}}$  effect), the output voltage of the first stage is (in Volts):

$$V_{OUT-} = (-V_{IN}) \frac{R_F}{R_{IN}}$$

For the second stage:  $V_{OUT+} = -V_{OUT-}(V)$ 

The differential output voltage is (in Volts):

$$V_{OUT^{+}} - V_{OUT^{-}} = 2V_{IN} \frac{R_{F}}{R_{IN}}$$

The differential gain,  $G_v$ , in shourt, is given by:

$$G_{v} = \frac{V_{OUT+} - V_{OUT-}}{V_{IN}} = 2\frac{R_{F}}{R_{IN}}$$

 $V_{\text{OUT+}}$  is in phase with  $V_{\text{IN}}$  and  $V_{\text{OUT-}}$  is phased 180° with  $V_{\text{IN}}$ . This means that the positive terminal of the loudspeaker should be connected to  $V_{\text{OUT+}}$  and the negative to  $V_{\text{OUT-}}$ .

### **LOW AND HIGH FREQUENCY RESPONSE**

In the low frequency region,  $C_{\text{IN}}$  starts to have an effect.  $C_{\text{IN}}$  forms with  $R_{\text{IN}}$  a high-pass filter with a -3dB cut-off frequency.  $f_{\text{CL}}$  is in Hz.

$$f_{CL} = \frac{1}{2\pi R_{IN} C_{IN}}$$

In the high frequency region, you can limit the bandwidth by adding a capacitor ( $C_F$ ) in parallel with  $R_F$ . It forms a low-pass filter with a -3dB cut-off frequency.  $f_{CH}$  is in Hz.

$$f_{CH} = \frac{1}{2\pi R_F C_F}$$

#### **DECOUPLING OF THE CIRCUIT**

Two capacitors are needed to correctly bypass the IS31AP4990D: a power supply bypass capacitor  $C_S$  and a bias voltage bypass capacitor  $C_{BYPASS}$ .

 $C_{\rm S}$  has particular influence on the THD+N in the high frequency region (above 7kHz) and an indirect influence on power supply disturbances. With a value for  $C_{\rm S}$  of 1µF, you can expect THD+N levels similar to those shown in the datasheet.

In the high frequency region, if  $C_S$  is lower than  $1\mu F$ , it increases THD+N and disturbances on the power supply rail are less filtered.

On the other hand, if  $C_S$  is higher than  $1\mu F$ , those disturbances on the power supply rail are more filtered.

C<sub>BYPASS</sub> has an influence on THD+N at lower frequencies, but its function is critical to the final result of PSRR (with input grounded and in the lower frequency region).

If  $C_{\text{BYPASS}}$  is lower than 1µF, THD+N increases at lower frequencies and PSRR worsens.

If  $C_{\text{BYPASS}}$  is higher than 1µF, the benefit on THD+N at lower frequencies is small, but the benefit to PSRR is substantial.

Note that  $C_{\text{IN}}$  has a non-negligible effect on PSRR at lower frequencies. The lower the value of  $C_{\text{IN}}$ , the higher the PSRR is.

#### WAKE-UP TIME (twu)

When the SDB pin is released to put the device ON, the bypass capacitor  $C_{BYPASS}$  will not be charged immediately. As  $C_{BYPASS}$  is directly linked to the bias of the amplifier, the bias will not work properly until the  $C_{BYPASS}$  voltage is correct. The time to reach this voltage is called wake-up time or  $t_{WU}$  and specified in the electrical characteristics table with  $C_{BYPASS} = 1 \mu F$ .

### **POP PERFORMANCE**

Pop performance is intimately linked with the size of the input capacitor  $C_{\text{IN}}$  and the bias voltage bypass capacitor  $C_{\text{BYPASS}}$ .

The size of  $C_{\text{IN}}$  is dependent on the lower cut-off frequency and PSRR values requested. The size of  $C_{\text{BYPASS}}$  is dependent on THD+N and PSRR values requested at lower frequencies.

Moreover,  $C_{\text{BYPASS}}$  determines the speed with which the amplifier turns ON.



### **CLASSIFICATION REFLOW PROFILES**

Profile Feature	Pb-Free Assembly		
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	150°C 200°C 60-120 seconds		
Average ramp-up rate (Tsmax to Tp)	3°C/second max.		
Liquidous temperature (TL) Time at liquidous (tL)	217°C 60-150 seconds		
Peak package body temperature (Tp)*	Max 260°C		
Time (tp)** within 5°C of the specified classification temperature (Tc)	Max 30 seconds		
Average ramp-down rate (Tp to Tsmax)	6°C/second max.		
Time 25°C to peak temperature	8 minutes max.		

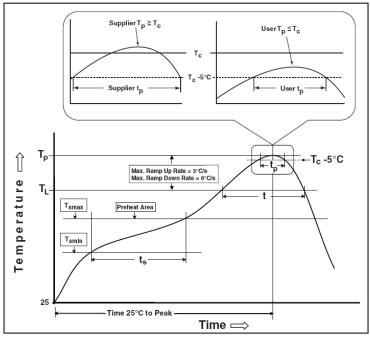
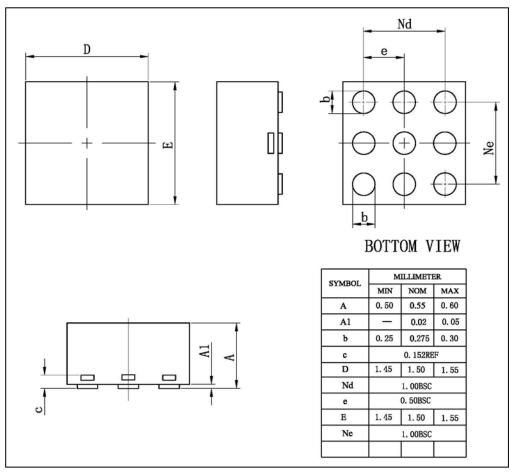


Figure 10 Classification Profile



# **PACKAGING INFORMATION**

### **UTQFN-9L**



Note: All dimensions in millimeters unless otherwise stated.